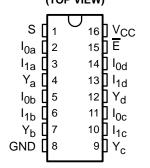
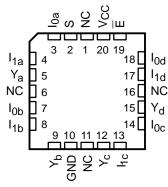
- **Function, Pinout, and Drive Compatible** With FCT and F Logic
- Reduced V_{OH} (Typically = 3.3 V) Versions of Equivalent FCT Functions
- **Edge-Rate Control Circuitry for** Significantly Improved Noise Characteristics
- Ioff Supports Partial-Power-Down Mode Operation
- **Matched Rise and Fall Times**
- Fully Compatible With TTL Input and **Output Logic Levels**
- **ESD Protection Exceeds JESD 22**
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)
- CY54FCT157T
 - 32-mA Output Sink Current
 - 12-mA Output Source Current
- CY74FCT157T
 - 64-mA Output Sink Current
 - 32-mA Output Source Current
- 3-State Outputs

CY74FCT157T . . . Q OR SO PACKAGE (TOP VIEW)



CY54FCT157T...L PACKAGE (TOP VIEW)



NC - No internal connection

description

The 'FCT157T devices are guad two-input multiplexers that select four bits of data from two sources under the control of a common data-select (S) input. The output-enable (\overline{E}) input is active low. When \overline{E} is high, all of the outputs (Y) are forced low, regardless of all other input conditions.

Moving data from two groups of registers to four common output buses is a common use of the 'FCT157T devices. The state of S determines the particular register from which the data comes. It also can be used as a function generator. These devices are useful for implementing highly irregular logic by generating any 4 of the 16 different functions of 2 variables, with 1 variable common.

The 'FCT157T devices are logic implementations of a four-pole, two-position switch, where the position of the switch is determined by the logic levels at S.

These devices are fully specified for partial-power-down applications using Ioff. The Ioff circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.



testing of all parameters.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



PIN DESCRIPTION

NAME	DESCRIPTION
S	Common select input
Ē	Enable inputs (active low)
I ₀	Data inputs from source 0
I ₁	Data inputs from source 1
Y	Noninverted outputs

ORDERING INFORMATION

TA	PACI	KAGET	SPEED (ns)	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	QSOP - Q	Tape and reel	4.3	CY74FCT157CTQCT	FT157-3
–40°C to 85°C	SOIC - SO	Tube	4.3	CY74FCT157CTSOC	FCT157C
	3010 - 30	Tape and reel	4.3	CY74FCT157CTSOCT	FC1157C
-40 C to 65 C	QSOP - Q	Tape and reel	5	CY74FCT157ATQCT	FT157-1
	SOIC - SO	Tube	5	CY74FCT157ATSOC	FCT157A
	3010 - 30	Tape and reel	5	CY74FCT157ATSOCT	FC1157A
–55°C to 125°C	LCC - L	Tube	5.8	CY54FCT157ATLMB	

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

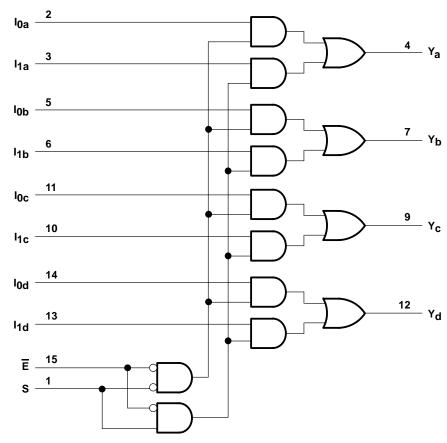
	INP	OUTPUT		
Ē	S	l ₀	l ₁	Υ
Н	Χ	Х	Х	L
L	Н	Χ	L	L
L	Н	Χ	Н	Н
L	L	L	X	L
L	L	Н	Χ	Н

H = High logic level, L = Low logic level, X = Don't care



SCCS014B - MAY 1994 - REVISED NOVEMBER 2001

logic diagram (positive logic)



Pin numbers shown are for the Q and SO packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range to ground potential	0.5 V to 7 V
DC input voltage range	0.5 V to 7 V
DC output voltage range	0.5 V to 7 V
DC output current (maximum sink current/pin)	120 mA
Package thermal impedance, θ _{JA} (see Note 1): Q package	90°C/W
SO package	57°C/W
Ambient temperature range with power applied, T _A	–65°C to 135°C
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.



CY54FCT157T, CY74FCT157T QUAD 2-INPUT MULTIPLEXERS WITH 3-STATE OUTPUTS

SCCS014B - MAY 1994 - REVISED NOVEMBER 2001

recommended operating conditions (see Note 2)

		CY	54FCT15	7T	CY	74FCT15	7T	UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			8.0			0.8	V
loh	High-level output current			-12			-32	mA
l _{OL}	Low-level output current			32			64	mA
TA	Operating free-air temperature	-55		125	-40		85	°C

NOTE 2: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETER		TEST SOUDITION	CY	54FCT15	57T	CY	74FCT15	57T	UNIT						
PARAMETER		TEST CONDITION	NS	MIN	TYP	MAX	MIN	TYP†	MAX	UNII					
Vers	V _{CC} = 4.5 V,	I _{IN} = -18 mA			-0.7	-1.2				V					
VIK	V _{CC} = 4.75 V,	I _{IN} = -18 mA						-0.7	-1.2	V					
	$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -12 \text{ mA}$		2.4	3.3										
Voн	V _{CC} = 4.75 V	$I_{OH} = -32 \text{ mA}$					2			V					
	VCC = 4.75 V	$I_{OH} = -15 \text{ mA}$					2.4	3.3							
V _{OL}	$V_{CC} = 4.5 \text{ V},$	I_{OL} = 32 mA			0.3	0.55				V					
VOL	$V_{CC} = 4.75 \text{ V},$	$I_{OL} = 64 \text{ mA}$						0.3	0.55	V					
V _{hys}	All inputs				0.2			0.2		V					
lį	$V_{CC} = 5.5 \text{ V},$	VIN = VCC				5				μΑ					
'1	$V_{CC} = 5.25 \text{ V},$	VIN = VCC							5	μΑ					
ΊΗ	$V_{CC} = 5.5 \text{ V},$	$V_{IN} = 2.7 \text{ V}$				±1				μΑ					
ЧH	$V_{CC} = 5.25 \text{ V},$	V _{IN} = 2.7 V							±1	μΛ					
IIL	$V_{CC} = 5.5 \text{ V},$	V _{IN} = 0.5 V			-	±1				μΑ					
'IL	$V_{CC} = 5.25 \text{ V},$	V _{IN} = 0.5 V							±1	μπ					
IOZH	$V_{CC} = 5.5 \text{ V},$					10				μΑ					
10211	$V_{CC} = 5.25 \text{ V},$	V _{OUT} = 2.7 V							10	μπ					
lozL	$V_{CC} = 5.5 \text{ V},$	V _{OUT} = 0.5 V				-10				μΑ					
-OZL	$V_{CC} = 5.25 \text{ V},$	V _{OUT} = 0.5 V							-10	μπ					
los‡	$V_{CC} = 5.5 \text{ V},$	$V_{OUT} = 0 V$		-60	-120	-225				mA					
1051	$V_{CC} = 5.25 \text{ V},$	$V_{OUT} = 0 V$			-		-60	-120	-225	1117 (
l _{off}	$V_{CC} = 0 V$,	V _{OUT} = 4.5 V				±1			±1	μΑ					
loc	$V_{CC} = 5.5 \text{ V},$	$V_{IN} \le 0.2 V$,	$V_{IN} \ge V_{CC} - 0.2 V$		0.1	0.2				mA					
Icc	$V_{CC} = 5.25 V$,	$V_{IN} \le 0.2 V$,	$V_{IN} \ge V_{CC} - 0.2 \text{ V}$					0.1	0.2	.2					
Alee	$V_{CC} = 5.5 \text{ V}, V_{IN}$	$_{\text{N}} = 3.4 \text{ V}, \ \text{f}_{1} = 0, \text{ O}$		0.5	2				mA						
ΔICC	V _C C = 5.25 V, V _I	$IN = 3.4 \text{ V}$, $f_1 = 0, C$	Outputs open					0.5	2	IIIA					

[†] Typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



[‡] Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample-and-hold techniques are preferable to minimize internal chip heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output can raise the chip temperature well above normal and cause invalid readings in other parametric tests. In any sequence of parameter tests, IOS tests should be performed last.

Per TTL-driven input (VIN = 3.4 V); all other inputs at VCC or GND

SCCS014B - MAY 1994 - REVISED NOVEMBER 2001

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (continued)

DADAMETER		TEST CONDITION	10	CY	54FCT15	7T	CY	74FCT15	7T	LINUT
PARAMETER		TEST CONDITION	3	MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNIT
1000		e input switching at 50 = GND, $V_{IN} \le 0.2 \text{ V}$ or			0.06	0.12				mA/
ICCD¶		ne input switching at 5 = GND, $V_{IN} \le 0.2 \text{ V}$ or					0.06	0.12	MHz	
		One input switching at f ₁ = 10 MHz	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$		0.7	1.4				
$V_{CC} = 5.5 \text{ V},$ Outputs open, $\overline{E} = \text{GND}$	at 50% duty cycle	V _{IN} = 3.4 V or GND		1	2.4					
		Four bits switching at f ₁ = 2.5 MHz	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$		0.7	1.4				
IC#		at 50% duty cycle	$V_{IN} = 3.4 \text{ V or GND}$		1.7	5.4				mA
10"		One input switching at f ₁ = 10 MHz	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$					0.7	1.4	IIIA
	V _{CC} = 5.25 V, Outputs open,	at 50% duty cycle	V _{IN} = 3.4 V or GND					1	2.4	
	E = GND		$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$					0.7	1.4	
		at 50% duty cycle	$V_{IN} = 3.4 \text{ V or GND}$					1.7	5.4	
Ci					5	10		5	10	pF
Co					9	12		9	12	pF

 $[\]overline{\dagger}$ Typical values are at V_{CC} = 5 V, T_A = 25°C.

Where:

IC = Total supply current

I_{CC} = Power-supply current with CMOS input levels

 ΔI_{CC} = Power-supply current for a TTL high input (V_{IN} = 3.4 V)

D_H = Duty cycle for TTL inputs high N_T = Number of TTL inputs at D_H

I_{CCD} = Dynamic current caused by an input transition pair (HLH or LHL)

= Clock frequency for registered devices, otherwise zero

f₁ = Input signal frequency

N₁ = Number of inputs changing at f₁

All currents are in milliamperes and all frequencies are in megahertz.

|| Values for these conditions are examples of the I_{CC} formula.

switching characteristics over operating free-air temperature range (see Figure 1)

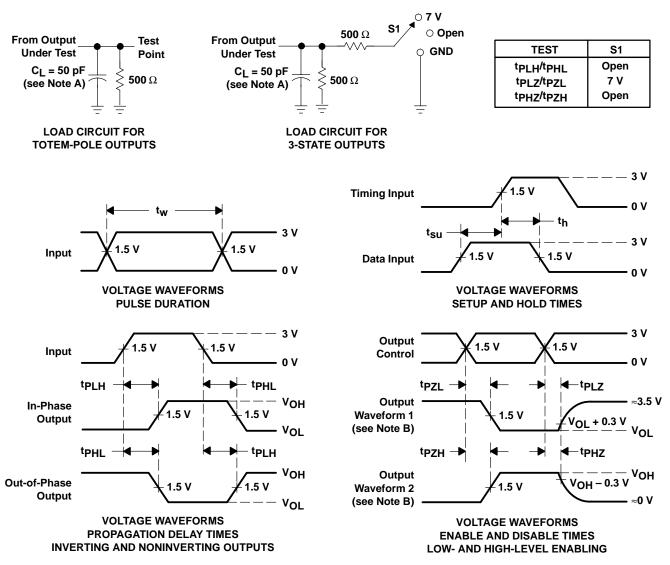
PARAMETER	FROM	то	CY54FC	CY54FCT157AT		CY74FCT157AT		CY74FCT157CT	
PARAMETER	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
tPLH		V	1.5	5.8	1.5	5	1.5	4.3	no
t _{PHL}	I	Ť	1.5	5.8	1.5	5	1.5	4.3	ns
tPLH	<u> </u>	V	1.5	7.4	1.5	6	1.5	4.8	ns
t _{PHL}	E	Ť	1.5	7.4	1.5	6	1.5	4.8	115
t _{PLH}	s	V	1.5	8.1	1.5	7	1.5	5.2	ns
^t PHL	3	ſ	1.5	8.1	1.5	7	1.5	5.2	115



This parameter is derived for use in total power-supply calculations.

 $^{^{\#}}$ IC = ICC + Δ ICC \times DH \times NT + ICCD ($f_0/2 + f_1 \times N_1$)

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



www.ti.com 18-Nov-2023

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9220803M2A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9220803M2A	Samples
CY74FCT157ATDR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT157AT	Samples
CY74FCT157ATSOC	ACTIVE	SOIC	DW	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT157A	Samples
CY74FCT157CTD	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT157CT	Samples
CY74FCT157CTQCT	ACTIVE	SSOP	DBQ	16	2500	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FT157-3	Samples
CY74FCT157CTSOC	ACTIVE	SOIC	DW	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT157C	Samples
CY74FCT157CTSOCT	ACTIVE	SOIC	DW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT157C	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



PACKAGE OPTION ADDENDUM

www.ti.com 18-Nov-2023

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

www.ti.com 30-Nov-2023

TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CY74FCT157ATDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CY74FCT157CTQCT	SSOP	DBQ	16	2500	330.0	12.5	6.4	5.2	2.1	8.0	12.0	Q1
CY74FCT157CTSOCT	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1



www.ti.com 30-Nov-2023



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CY74FCT157ATDR	SOIC	D	16	2500	340.5	336.1	32.0
CY74FCT157CTQCT	SSOP	DBQ	16	2500	340.5	338.1	20.6
CY74FCT157CTSOCT	SOIC	DW	16	2000	350.0	350.0	43.0

PACKAGE MATERIALS INFORMATION

www.ti.com 30-Nov-2023

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-9220803M2A	FK	LCCC	20	55	506.98	12.06	2030	NA
CY74FCT157ATSOC	DW	SOIC	16	40	506.98	12.7	4826	6.6
CY74FCT157CTD	D	SOIC	16	40	507	8	3940	4.32
CY74FCT157CTSOC	DW	SOIC	16	40	506.98	12.7	4826	6.6

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2023, Texas Instruments Incorporated